Product data sheet

1. General description

Silicon Carbide Schottky diode in a TO247-2L plastic package, designed for high frequency switched-mode power supplies.



2. Features and benefits

- · Highly stable switching performance
- High forward surge capability I_{FSM}
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- · Reduced cooling requirements
- RoHS compliant
- High junction operating temperature capability (T_{i(max)} = 175 °C)

3. Applications

- · Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values		Unit	
Absolute	maximum rating						
V_{RRM}	repetitive peak reverse voltage				1200		V
l _F	continuous forward current	T _{mb} ≤ 133 °C; DC; <u>Fig. 2</u>			30		А
T _j	junction temperature			-55 to 175		°C	
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics		'				
V _F	forward voltage	I _F = 30 A; T _j = 25 °C; <u>Fig. 5</u>		-	1.42	1.60	V
		I _F = 30 A; T _j = 150 °C; <u>Fig. 5</u>		-	1.90	2.30	V
		I _F = 30 A; T _j = 175 °C; <u>Fig. 5</u>		-	2.00	2.50	V
Dynamic	characteristics		'		'	,	
Q_r	recovered charge	$I_F = 30 \text{ A}$; $dI_F/dt = 500 \text{ A/}\mu\text{s}$; $V_R = 400 \text{ V}$; $T_j = 25 ^{\circ}\text{C}$; Fig. 7		-	68	-	nC

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		1/ 1/4 A
2	А	anode		K — A 001aaa020
mb	mb	mounting base; connected to cathode	K A TO247-2L	

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC2D301200W	TO247-2L	WNSC2D301200W6Q	Tube		TO247L-2L(L) TO247L-2L(P)	

7. Marking

Table 4. Marking codes

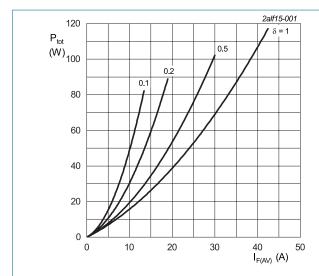
Type number	Marking codes
WNSC2D301200W	WNSC2D
	301200W

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			1200	V
V_{RWM}	crest working reverse voltage			1200	V
V_R	reverse voltage	DC		1200	V
I _F	continuous forward	T _{mb} ≤ 133 °C; DC; <u>Fig. 2</u>		30	Α
	current	T _{mb} ≤ 125°C; DC; <u>Fig. 2</u>		34	Α
		T _{mb} ≤ 25°C; DC; <u>Fig. 2</u>		68	Α
I _{FRM}	repetitive peak forward current	$δ = 0.5$; $t_p = 25 \mu s$; $T_{mb} \le 125 °C$; square-wave pulse		53	А
I _{FSM}	non-repetitive peak	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		270	Α
	forward current	t_p = 10 μ s; $T_{j(init)}$ = 25 °C; square-wave pulse		1500	Α
l ² t	I ² t for fusing	sine-wave pulse; $T_{j(init)}$ = 25 °C; t_p = 10 ms		364.5	A ² s
T _{stg}	storage temperature			-55 to 175	°C
T _j	junction temperature			-55 to 175	°C



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$ $V_o = 1.200 \text{ V}; R_s = 0.0368 \Omega$ Fig. 1. Forward power dissipation as a

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

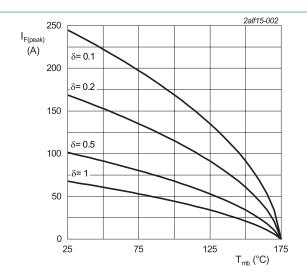
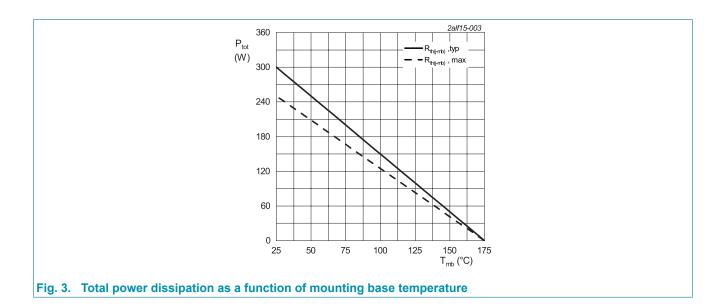


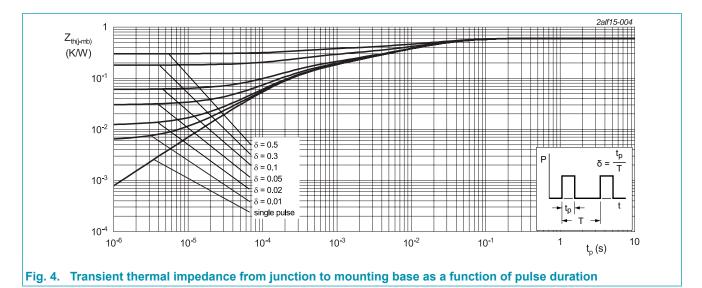
Fig. 2. Current derating as a function of mounting base temperature



9. Thermal characteristics

Table 6. Thermal characteristics

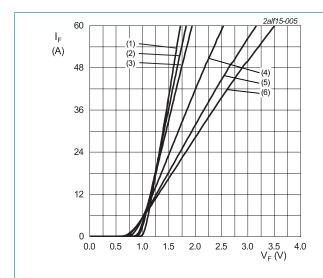
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base	Fig. 4		-	0.5	0.6	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air		-	40	-	K/W



10. Characteristics

Table 7. Characteristics

	1 =		1				
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static cha	aracteristics						
V_{F}	forward current	I _F = 30 A; T _j = 25 °C; <u>Fig. 5</u>		-	1.42	1.60	V
		I _F = 30 A; T _j = 150 °C; <u>Fig. 5</u>		-	1.90	2.30	V
		I _F = 30 A; T _j = 175 °C; <u>Fig. 5</u>		-	2.00	2.50	V
I _R	reverse current	V _R = 1200 V; T _j = 25 °C; <u>Fig. 6</u>		-	1	150	μΑ
		V _R = 1200 V; T _j = 175 °C; <u>Fig. 6</u>		-	50	1500	μΑ
Dynamic	characteristics						
Q_r	recovered charge	$I_F = 30 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$		-	68	-	nC
C _d	diode capacitance	f = 1 MHz; V _R = 1 V; T _j = 25 °C		-	1407	-	pF
		f = 1 MHz; V _R = 400 V; T _j = 25 °C		-	125	-	pF
		f = 1 MHz; V _R = 800 V; T _j = 25 °C		-	93	-	pF
E _{as}	non-repetitive avalanche energy	$I_R = 8 \text{ A}; L = 10 \text{ mH}; T_{j(init)} = 25 \text{ °C}$		300	-	-	mJ



 $V_0 = 1.200 \text{ V}; R_s = 0.0368 \Omega$

(1) T_i = -55 °C; typical values

(2) T_i = 0 °C; typical values

(3) T_j = 25 °C; typical values (4) T_j = 100 °C; typical values

(5) $T_j = 150$ °C; typical values

(6) T_i = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

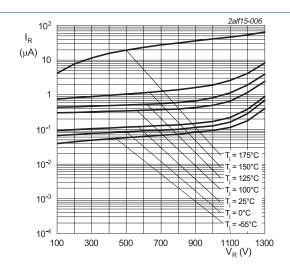


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

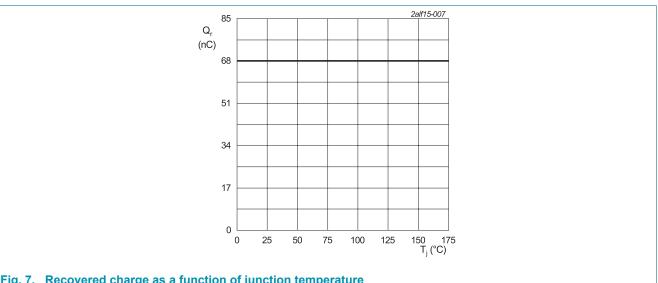
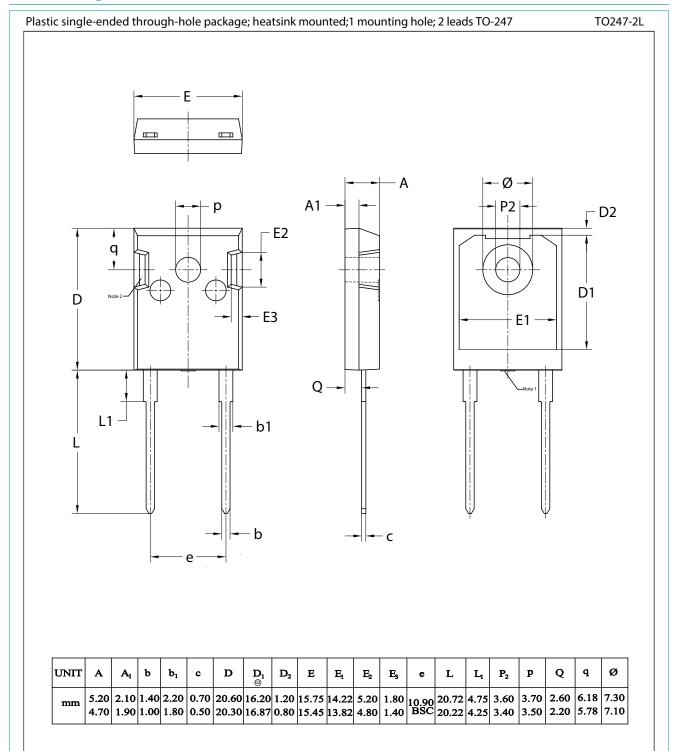


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline



Note:

- 1. Mold resin protrusion max 0.127mm.
- 2. Metal exposed with Sn plating.

12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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